

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

Applicant(s): TAKETATSU, et al  
Application No.: 10/585,461  
Filed: July 7, 2006  
For: CIRCUIT CONNECTION MATERIAL, FILM-SHAPED CIRCUIT  
CONNECTION MATERIAL USING THE SAME, CIRCUIT MEMBER  
CONNECTION STRUCTURE, AND MANUFACTURING METHOD THEREOF  
Confirmation No.: 5965

**RESPONSE TO NOTIFICATION OF MISSING REQUIREMENTS**

Mail Stop Missing Parts  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

May 27, 2009

Sir:

In response to the Notification of Missing Requirements dated April 16, 2009, in connection with the above-identified application, attached hereto is an executed Declaration for the above-identified patent application, in compliance with 37 CFR 1.63.

The fee of \$130.00 required to satisfy the requirements set forth in 37 CFR 1.16(f) is being submitted electronically at the time of filing this response.

Please charge any shortages in the fees due in connection with the filing of this paper, including extension of time fees, to Deposit Account No. 01-2135 (Docket No. 1303.46354X00) and please credit any excess fees to such deposit account.

Respectfully submitted,

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